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# PacketClock™ Spread Spectrum Clock Generator

#### **Features**

- Integrated phase-locked loop (PLL)
- Low jitter, high-accuracy outputs
- 3.3 V operation
- 25 MHz input frequency
- 33.33 MHz or 25 MHz selectable output frequency (-21)

#### **Benefits**

- High-performance PLL tailored for spread spectrum application
- Meets critical timing requirements in complex system designs
- Enables application compatibility
- Works with commonly available crystal or driven reference
- Downspread spread spectrum with 30 kHz nominal modulation frequency

#### **Functional Description**

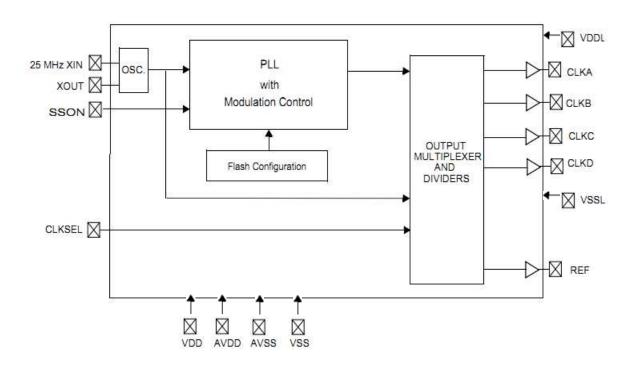
For a complete list of related resources, click here.

### **Frequency Table**

for CLKA-D

Part Number	CLKSEL = 0	CLKSEL = 1	Spread%	Parallel Crystal Load
CY26121-21	33.33 MHz	25.00	-2.8%	15 pF

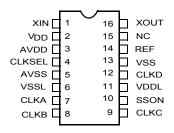
## **Logic Block Diagram**





# **Pin Configuration**

Figure 1. 16-pin TSSOP pinout



### **Pin Definitions**

Pin Name	Pin Number	Description
XIN	1	Reference input Or crystal input
VDD	2	3.3 V voltage supply
AVDD	3	3.3 V analog voltage
CLKSEL	4 (-21)	0 = 33.33 MHz out, 1 = 25 MHz Out. Weak pull-up.
AVSS	5	Analog ground
VSSL	6	CLK ground
CLK(A:D)	7, 8, 9, 12	Clock outputs at V <sub>DDL</sub> level
SSON	10	Spread spectrum enable pin 0 = SS off; 1 = SS on. Weak pull-up.
VDDL	11	3.3 V clock voltage supply
VSS	13	Ground
REF	14	Reference output at V <sub>DD</sub> level
NC	15	No connect
XOUT <sup>[1]</sup>	16	Crystal output

#### Notes

Float XOUT if XIN is externally driven.



## **Maximum Ratings**

Exceeding maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Supply voltage $(V_{DD}, AV_{DD}, V_{DDL})$	–0.5 to +7.0 V
DC input voltage	–0.5 V to V <sub>DD</sub> + 0.5 V

Storage temperature (Non-condensing)	–55 °C to +125 °C
Junction temperature	40 °C to +125 °C
Data retention at Tj = 125 °C	> 10 years
Package power dissipation	350 mW
Static discharge voltage (per MIL-STD-883, Method 3015)	<u>&gt;</u> 2000 V

# **Recommended Operating Conditions**

Parameter	Description	Min	Тур	Max	Unit
$V_{DD,} AV_{DD}$	Supply voltage	3.135	3.30	3.465	V
$V_{DDL}$	Supply voltage for CLK (A-D)	3.135	3.30	3.465	V
T <sub>A</sub>	Ambient temperature (industrial temp grade)	-40	_	85	°C
C <sub>LOAD</sub>	Max. output load capacitance	-	_	15	pF
F <sub>ref</sub>	Reference frequency	-	25	-	MHz

# **Crystal Specification**

Parameter [2]	Description	Min	Тур	Max	Unit
CR <sub>load</sub>	Crystal load capacitance (-21)	-	15	_	pF
ESR	Equivalent series resistance	_	1	50	Ω

## **DC Electrical Specifications**

Parameter	Description	Condition	Min	Тур	Max	Unit
I <sub>OH</sub>	Output high current	$V_{OH} = V_{DD} - 0.5 \text{ V}, V_{DD}/V_{DDL} = 3.3 \text{ V}$	12	24	_	mA
I <sub>OL</sub>	Output low current	$V_{OL} = 0.5 \text{ V}, V_{DD}/V_{DDL} = 3.3 \text{ V}$	12	24	_	mA
I <sub>IH</sub>	Input high current	$V_{IH} = V_{DD}$	_	5	10	μΑ
I <sub>IL</sub>	Input low current	V <sub>IL</sub> = 0 V	_	-	50	μΑ
V <sub>IH</sub>	Input high voltage	CMOS levels	0.7 × V <sub>DD</sub>	-	_	V
V <sub>IL</sub>	Input low voltage	CMOS levels	_	_	0.3 × V <sub>DD</sub>	V
C <sub>IN</sub> [3]	Input capacitance	Input pins excluding XIN	_	_	7	pF
R <sub>UP</sub> <sup>[3]</sup>	Pull-up resistor on input pins	$V_{DD}$ = 3.14 to 3.47 V, measured at $V_{IN}$ = 0 V	80	100	150	kΩ
I <sub>DD</sub>	Supply current	AV <sub>DD</sub> /V <sub>DD</sub> /V <sub>DDL</sub> Current.	_	42	60	mA

### **Thermal Resistance**

Parameter [3]	Description	Test Conditions	16-pin TSSOP	Unit
$\theta_{JA}$		Test conditions follow standard test methods and procedures for measuring thermal impedance, in		°C/W
$\theta_{ m JC}$	Thermal resistance (junction to case)	accordance with EIA/JESD51.	14	°C/W

#### Notes

- A fundamental parallel resonant crystal must be used.
   Guaranteed by Characterization, not 100% tested.
   These parameters are guaranteed by design and are not tested.



# **AC Electrical Specifications**

Parameter [4]	Description	Condition	Min	Тур	Max	Unit
DC	Output duty cycle	Duty Cycle is defined in Figure 2, 50% of V <sub>DD</sub>	45	50	55	%
ER	Rising edge rate	Output clock edge rate, measured from 20% to 80% of $V_{DD}$ , $C_{LOAD}$ = 15 pF. See Figure 3.	0.8	1.4	_	V/ns
EF	Falling edge rate	Output clock edge rate, measured from 80% to 20% of $V_{DD}$ , $C_{LOAD}$ = 15 pF. See Figure 3.	0.8	1.4	_	V/ns
tj	RMS clock cycle-to-cycle Jitter	RMS cycle-to-cycle jitter with spread on. Measured at V <sub>DD</sub> /2.	_	15	40	ps

# **Voltage and Timing Definitions**

Figure 2. Duty Cycle Definition

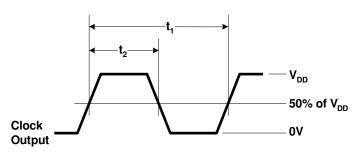
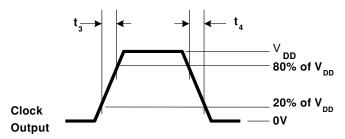


Figure 3. ER = (0.6 × V<sub>DD</sub>) / $t_3$ , EF = (0.6 × V<sub>DD</sub>) / $t_4$ 



#### Notes

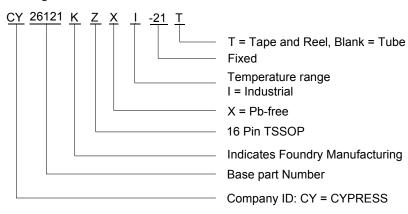
<sup>4.</sup> Guaranteed by Characterization, not 100% tested.



# **Ordering Information**

Ordering Code	Package Type	Operating Range
CY26121KZXI-21	16-pin TSSOP	Industrial, –40 °C to 85 °C
CY26121KZXI-21T	16-pin TSSOP – Tape and Reel	Industrial, –40 °C to 85 °C

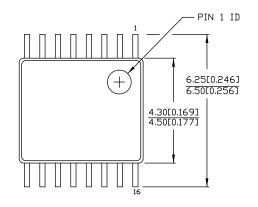
## **Ordering Code Definitions**





## **Package Drawing and Dimensions**

Figure 4. 16-pin TSSOP (4.40 mm Body) Z16.173/ZZ16.173 Package Outline, 51-85091

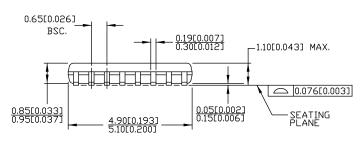


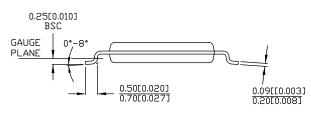
DIMENSIONS IN MMCINCHES) MIN. MAX.

REFERENCE JEDEC MO-153

PACKAGE WEIGHT 0.05gms

PART #				
Z16.173	STANDARD PKG.			
ZZ16.173	LEAD FREE PKG.			





51-85091 \*E



## **Acronyms**

Table 1. Acronyms Used in this Document

Acronym	Description
ESR	Equivalent Series Resistance
PLL	Phase-Locked Loop
TSSOP	Thin-Shrunk Small Outline Package

## **Document Conventions**

#### **Units of Measure**

Table 2. Units of Measure

Symbol	Unit of Measure			
°C	degree Celsius			
kΩ	kilohm			
MHz	megahertz			
μA	microampere			
mA	milliampere			
mW	milliwatt			
ns	nanosecond			
Ω	ohm			
%	percent			
pF	picofarad			
ps	picosecond			
V	volt			



# **Document History Page**

Document Title: CY26121, PacketClock™ Spread Spectrum Clock Generator Document Number: 38-07350					
Rev.	ECN No.	Issue Date	Orig. of Change	Description of Change	
**	121669	02/11/03	CKN	New data sheet.	
*A	2440886	See ECN	KVM / AESA	Updated Ordering Information: Added part numbers CY26121ZXC-21, CY26121ZXC-21T, CY26121ZXI-21, and CY26121ZXI-21T. Added part numbers CY26121KZC-21, CY26121KZC-21T, CY26121KZI-21, and CY26121KZI-21T. Added part numbers CY26121KZXC-21, CY26121KZXC-21T, CY26121KZXI-21, and CY26121KZXI-21T. Removed part numbers CY26121KZXI-21T. Removed part numbers CY26121ZI-11, CY26121ZI-11T, CY26121ZI-31 and CY26121ZI-31T. Added Note "Not recommended for new designs." and referred in some MPNs Updated to new template.	
*B	2899683	03/26/10	KVM	Removed reference to -2, -3, -11, -31 parts in all instances across the document.  Updated Ordering Information: Removed inactive parts. Removed Note "Not recommended for new designs." and its references. Updated Package Drawing and Dimensions.	
*C	3383431	09/26/2011	PURU	Updated Logic Block Diagram. Added Ordering Code Definitions under Ordering Information. Updated Package Drawing and Dimensions. Added Acronyms and Units of Measure.	
*D	4556342	10/30/2014	TAVA	Updated Package Drawing and Dimensions: spec 51-85091 – Changed revision from *C to *E. Updated to new template. Completing Sunset Review.	
*E	5279177	05/20/2016	PSR	Added Thermal Resistance. Updated to new template.	



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